

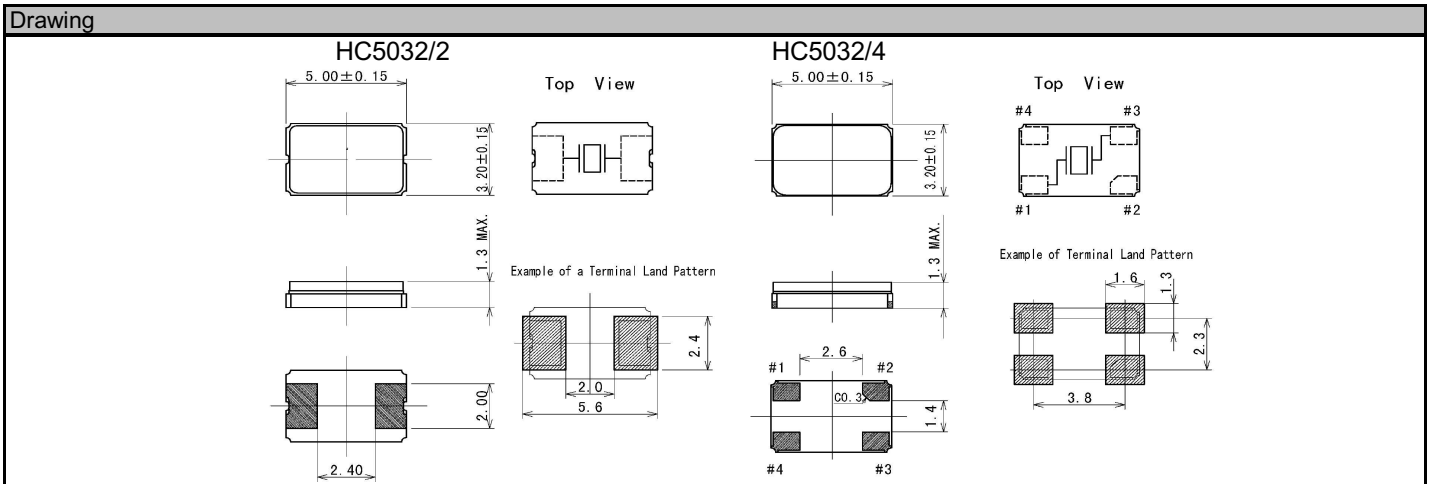
HC5032/2
HC5032/4

Features:

- Application: Bluetooth, wireless LAN
- Ultra-thin and small leadless type
- Automatic mounting is enabled by emboss taping
- Reflow soldering

Specifications				
		Symbol	HC5032	Remarks
Frequency range		f	12.000MHz ~ 50.000MHz 40.000MHz ~ 80.000 MHz	Fundamental mode 3rd. OT
Frequency tolerance, Ta=25°C		f/f	± 30ppm ~ ±50ppm	Please specify
Load capacitance		C _L	10pF ~ 32pF	Please specify
Temperature tolerance		f/f	± 30ppm ~ ± 50ppm	Please specify
Temperature range	Storage temperature	T _{STG}	-55°C ~ +125°C	
	Operating temperature	T _{OPR}	-20°C ~ +70°C	Others are offered
Drive level	Maximum drive level	M _{DL}	300 W	
	Recommended drive level	R _{DL}	10 W ~ 100 W	
Series resistance		R ₁	As per table	25°C
Shunt capacitance		C ₀	5pF	
Insulation resistance		I _R	500M Ohm	
Aging		f _A	±3 ~ ± 5ppm/Year	

Resistance of series resonance (ESR)					
Frequency (MHz)	Mode	Ohm	Frequency (MHz)	Mode	Ohm
12 ~ 16	Fundamental	60	25 ~ 50	Fundamental	35
16 ~ 25	Fundamental	50	40 ~ 80	3rd OT	100



Order key								
Q	- 40.000000M	- HC5032/2	- F	- 50	- 50	- D	- 30	- TR
Part	Frequency	Package	Mode of oscillation	Frequency tolerance	Temperature tolerance	Temperature range	Load capacitance	Option
Q=Quartz	M=MHz	HC5032/2 HC5032/4	F=fund. 3=3.OT	+/-ppm (25°C)	+/-ppm (Temp. range)	A= 0°C ~ 70°C B=-10°C ~ 60°C C=-10°C ~ 70°C D=-20°C ~ 70°C E=-40°C ~ 85°C H=-20°C ~ +80°C I=-10°C ~ +50°C	pF SR=series	TR=Tape and reel X=Special options
		/2 = 2 pads /4 = 4 pads						

Remarks: All specifications subject to change without notice!